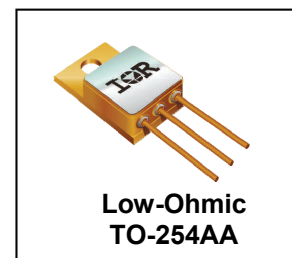


**RADIATION HARDENED
POWER MOSFET
THRU-HOLE (Low-Ohmic TO-254AA)**
200V, P-CHANNEL
REF: MIL-PRF-19500/713
 **R5 TECHNOLOGY**
Product Summary

Part Number	Radiation Level	RDS(on)	I _D	QPL Part Number
IRHMS597260	100 kRads(Si)	0.103Ω	-30A	JANSR2N7549T1
IRHMS593260	300 kRads(Si)	0.103Ω	-30A	JANSF2N7549T1


Description

IR HiRel R5 technology provides high performance power MOSFETs for space applications. These devices have been characterized for Single Event Effects (SEE) with useful performance up to an LET of 80 (MeV/(mg/cm²)). The combination of low RDS(on) and low gate charge reduces the power losses in switching applications such as DC to DC converters and motor control. These devices retain all of the well established advantages of MOSFETs such as voltage control, fast switching and temperature stability of electrical parameters.

Features

- Low RDS(on)
- Fast Switching
- Single Event Effect (SEE) Hardened
- Low Total Gate Charge
- Simple Drive Requirements
- Hermetically Sealed
- Ceramic Eyelets
- Electrically Isolated
- Light Weight
- ESD Rating: Class 3A per MIL-STD-750, Method 1020

Absolute Maximum Ratings
Pre-Irradiation

Symbol	Parameter	Value	Units
I _{D1} @ V _{GS} = -12V, T _C = 25°C	Continuous Drain Current	-30	A
I _{D2} @ V _{GS} = -12V, T _C = 100°C	Continuous Drain Current	-19	
I _{DM} @ T _C = 25°C	Pulsed Drain Current ①	-120	
P _D @ T _C = 25°C	Maximum Power Dissipation	208	W
	Linear Derating Factor	1.67	W/°C
V _{GS}	Gate-to-Source Voltage	± 20	V
E _{AS}	Single Pulse Avalanche Energy ②	332	mJ
I _{AR}	Avalanche Current ①	-30	A
E _{AR}	Repetitive Avalanche Energy ①	20.8	mJ
dv/dt	Peak Diode Recovery dv/dt ③	-4.1	V/ns
T _J T _{STG}	Operating Junction and Storage Temperature Range	-55 to + 150	°C
	Lead Temperature	300 ((0.063in./1.6mm from case for 10s)	
	Weight	9.3 (Typical)	g

For Footnotes, refer to the page 2.

Pre-Irradiation

Electrical Characteristics @ T_J = 25°C (Unless Otherwise Specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV _{DSS}	Drain-to-Source Breakdown Voltage	-200	—	—	V	V _{GS} = 0V, I _D = -1.0mA
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temp. Coefficient	—	-0.25	—	V/°C	Reference to 25°C, I _D = -1.0mA
R _{DS(on)}	Static Drain-to-Source On-State Resistance	—	—	0.103	Ω	V _{GS} = -12V, I _{D2} = -19A ④
V _{GS(th)}	Gate Threshold Voltage	-2.0	—	-4.0	V	V _{DS} = V _{GS} , I _D = -1.0mA
G _{fs}	Forward Transconductance	23	—	—	S	V _{DS} = -15V, I _{D2} = -19A ④
I _{DSS}	Zero Gate Voltage Drain Current	—	—	-10	μA	V _{DS} = -160V, V _{GS} = 0V
		—	—	-25		V _{DS} = -160V, V _{GS} = 0V, T _J = 125°C
I _{GSS}	Gate-to-Source Leakage Forward	—	—	-100	nA	V _{GS} = -20V
	Gate-to-Source Leakage Reverse	—	—	100		V _{GS} = 20V
Q _G	Total Gate Charge	—	—	180	nC	I _{D1} = -30A
Q _{GS}	Gate-to-Source Charge	—	—	75		V _{DS} = -100V
Q _{GD}	Gate-to-Drain ('Miller') Charge	—	—	50		V _{GS} = -12V
t _{d(on)}	Turn-On Delay Time	—	—	35	ns	V _{DD} = -100V
t _r	Rise Time	—	—	100		I _{D1} = -30A
t _{d(off)}	Turn-Off Delay Time	—	—	100		R _G = 1.20Ω
t _f	Fall Time	—	—	120		V _{GS} = -12V
L _S + L _D	Total Inductance	—	6.8	—	nH	Measured from Drain lead (6mm /0.25in. from package) to Source lead (6mm /0.25in. from package) with Source wires internally bonded from Source Pin to Drain Pad
C _{iss}	Input Capacitance	—	7170	—	pF	V _{GS} = 0V
C _{oss}	Output Capacitance	—	920	—		V _{DS} = -25V
C _{rss}	Reverse Transfer Capacitance	—	86	—		f = 1.0MHz

Source-Drain Diode Ratings and Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)	—	—	-30	A	
I _{SM}	Pulsed Source Current (Body Diode) ①	—	—	-120		
V _{SD}	Diode Forward Voltage	—	—	-5.0	V	T _J = 25°C, I _S = -47A, V _{GS} = 0V ④
t _{rr}	Reverse Recovery Time	—	—	300	ns	T _J = 25°C, I _F = -47A, V _{DD} ≤ -50V
Q _{rr}	Reverse Recovery Charge	—	—	6.0	μC	di/dt = 100A/μs ④
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L _S +L _D)				

Thermal Resistance

Symbol	Parameter	Min.	Typ.	Max.	Units
R _{θJC}	Junction-to-Case	—	—	0.60	°C/W
R _{θJCS}	Case -to- Sink	—	0.21	—	
R _{θJA}	Junction-to-Ambient (Typical socket mount)	—	—	48	

Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ② V_{DD} = -50V, starting T_J = 25°C, L = 0.73mH, Peak I_L = -30A, V_{GS} = -12V
- ③ I_{SD} ≤ -30A, di/dt ≤ -220A/μs, V_{DD} ≤ -200V, T_J ≤ 150°C
- ④ Pulse width ≤ 300 μs; Duty Cycle ≤ 2%
- ⑤ Total Dose Irradiation with V_{GS} Bias. -12 volt V_{GS} applied and V_{DS} = 0 during irradiation per MIL-STD-750, Method 1019, condition A.
- ⑥ Total Dose Irradiation with V_{DS} Bias. -160 volt V_{DS} applied and V_{GS} = 0 during irradiation per MIL-STD-750, Method 1019, condition A.

Radiation Characteristics

IR HiRel radiation hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at IR HiRel is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

Table1. Electrical Characteristics @ Tj = 25°C, Post Total Dose Irradiation ⑤⑥

Symbol	Parameter	100 kRads (Si) ¹		300 kRads (Si) ²		Units	Test Conditions
		Min.	Max.	Min.	Max.		
BV _{DSS}	Drain-to-Source Breakdown Voltage	-200	—	-200	—	V	V _{GS} = 0V, I _D = -1.0mA
V _{GS(th)}	Gate Threshold Voltage	-2.0	-4.0	-2.0	-5.0	V	V _{DS} = V _{GS} , I _D = -1.0mA
I _{GSS}	Gate-to-Source Leakage Forward	—	-100	—	-100	nA	V _{GS} = -20V
I _{GSS}	Gate-to-Source Leakage Reverse	—	100	—	100	nA	V _{GS} = 20V
I _{DSS}	Zero Gate Voltage Drain Current	—	-10	—	-10	μA	V _{DS} = -160V, V _{GS} = 0V
R _{DS(on)}	Static Drain-to-Source ④ On-State Resistance (TO-3)	—	0.103	—	0.103	Ω	V _{GS} = -12V, I _{D2} = -19A
R _{DS(on)}	Static Drain-to-Source ④ On-State Resistance (TO-254AA)	—	0.103	—	0.103	Ω	V _{GS} = -12V, I _{D2} = -19A
V _{SD}	Diode Forward Voltage	—	-5.0	—	-5.0	V	V _{GS} = 0V, I _S = -30A

1. Part number IRHMS597260 (JANSR2N7549T1)
2. Part numbers IRHMS593260 (JANSF2N7549T1)

IR HiRel radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

Table 2. Typical Single Event Effect Safe Operating Area

LET (MeV/(mg/cm ²))	Energy (MeV)	Range (μm)	VDS (V)				
			@VGS=0V	@VGS=5V	@VGS=10V	@VGS=15V	@VGS=20V
38 ± 5%	270 ± 7.5%	35 ± 7.5%	-200	-200	-200	-200	-75
61 ± 5%	330 ± 7.5%	31 ± 7.5%	-200	-200	-200	-50	—
84 ± 5%	350 ± 10%	28 ± 7.5%	-200	-200	-200	-35	—

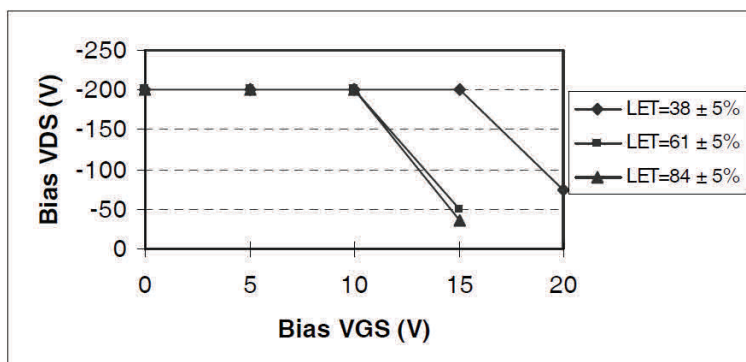


Fig a. Typical Single Event Effect, Safe Operating Area

For Footnotes, refer to the page 2.

Pre-Irradiation

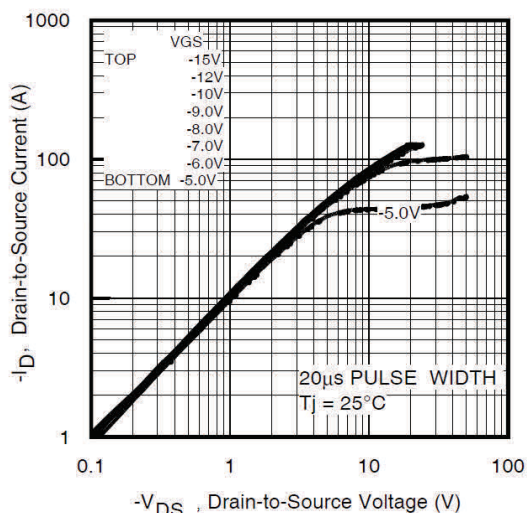


Fig 1. Typical Output Characteristics

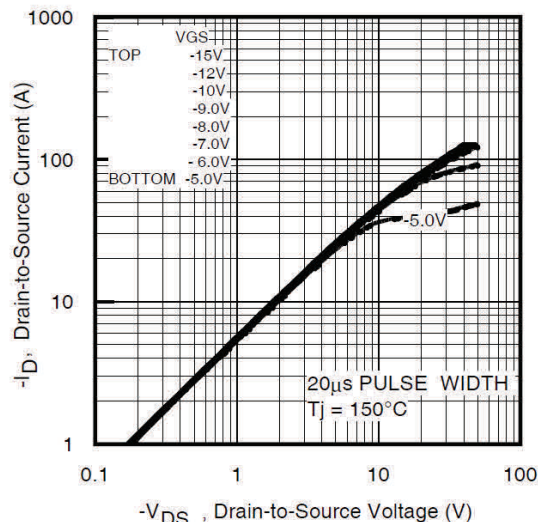


Fig 2. Typical Output Characteristics

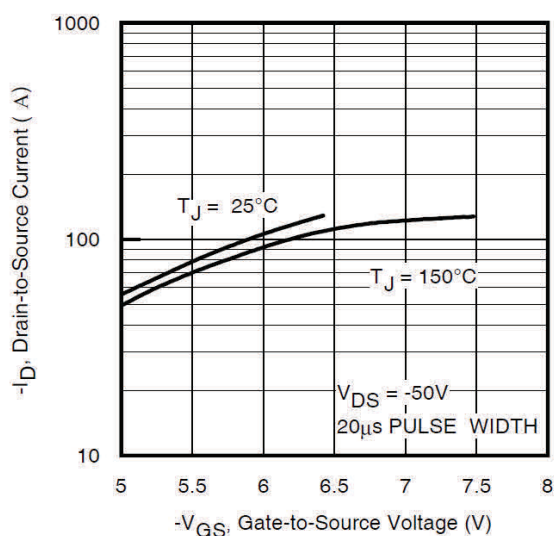


Fig 3. Typical Transfer Characteristics

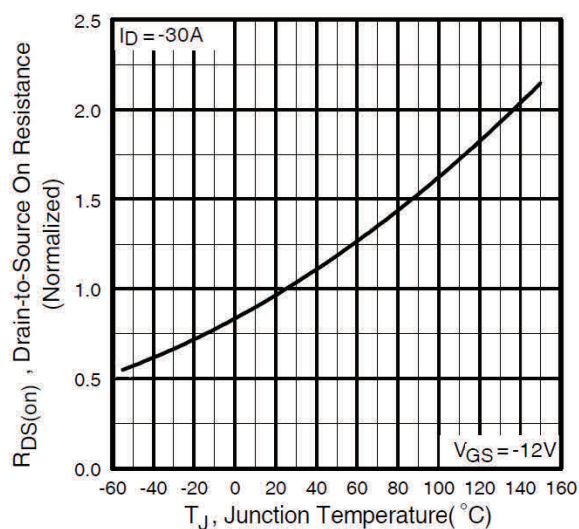


Fig 4. Normalized On-Resistance Vs. Temperature

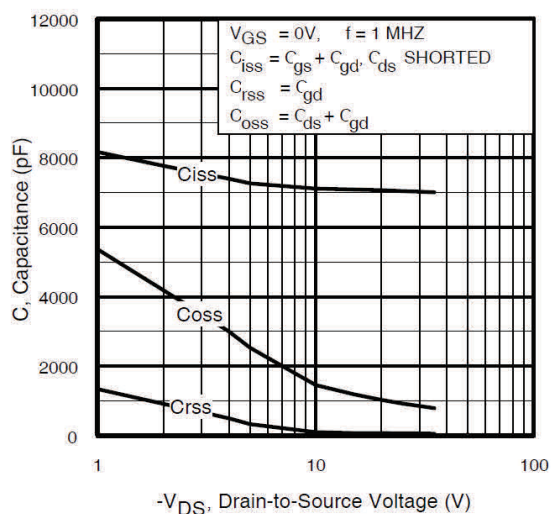


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

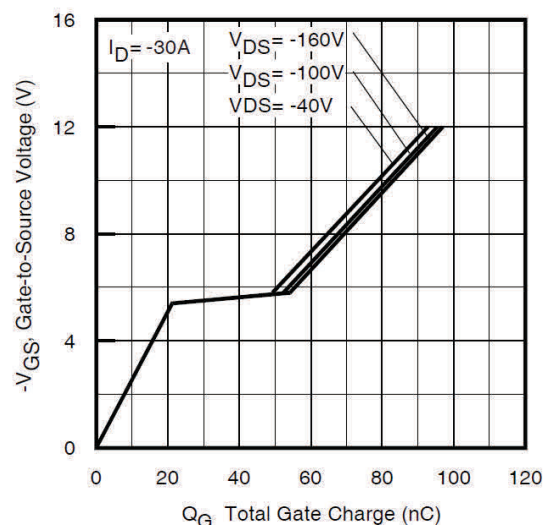


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

Pre-Irradiation

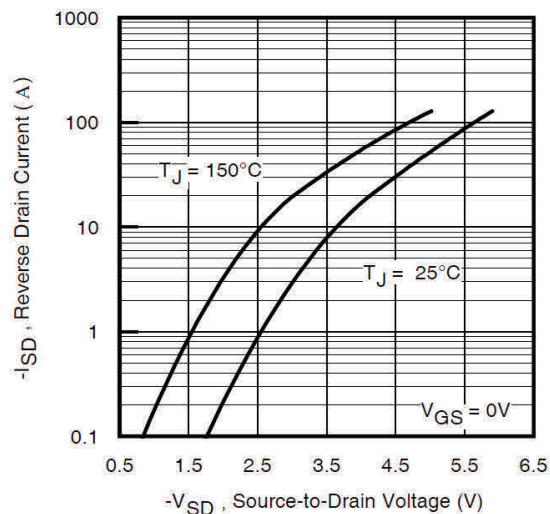


Fig 7. Typical Source-Drain Diode Forward Voltage

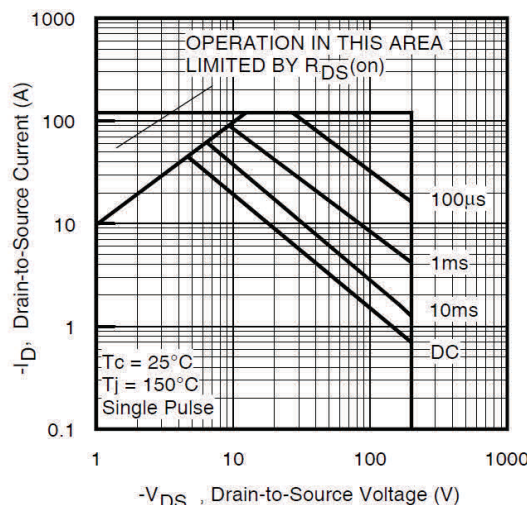


Fig 8. Maximum Safe Operating Area

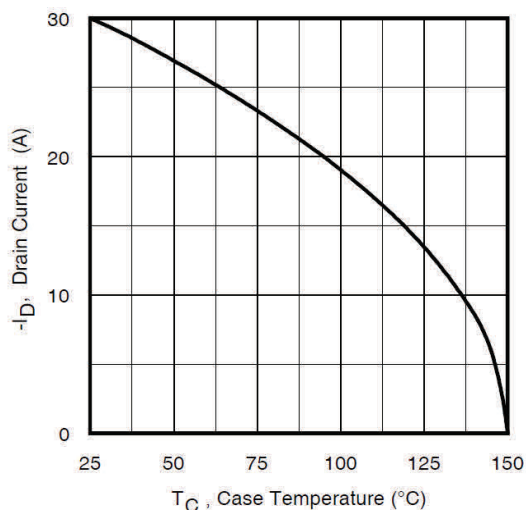


Fig 9. Maximum Drain Current Vs. Case Temperature

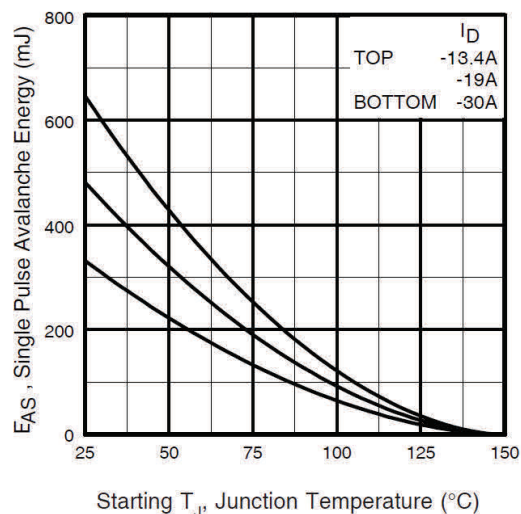


Fig 10. Maximum Avalanche Energy Vs. Drain Current

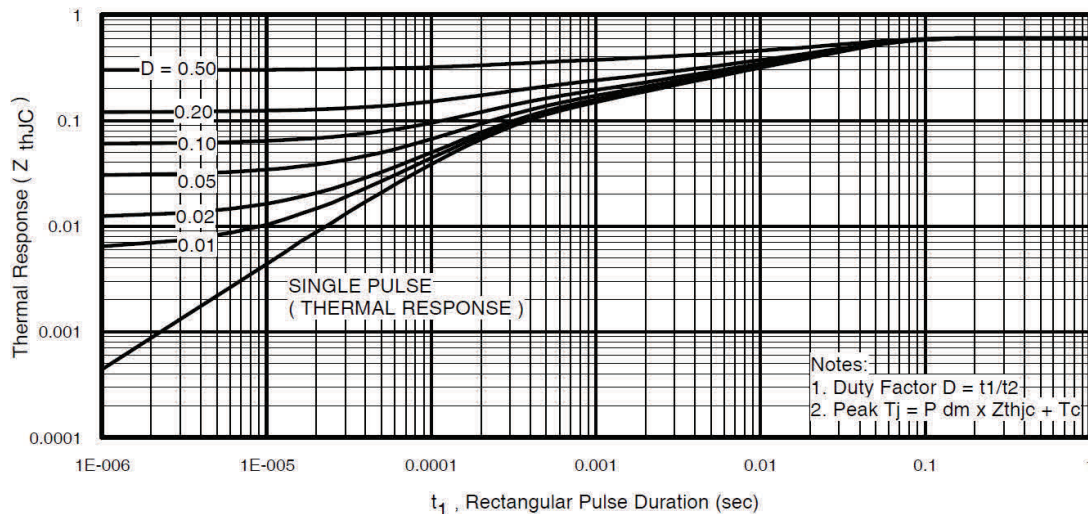


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

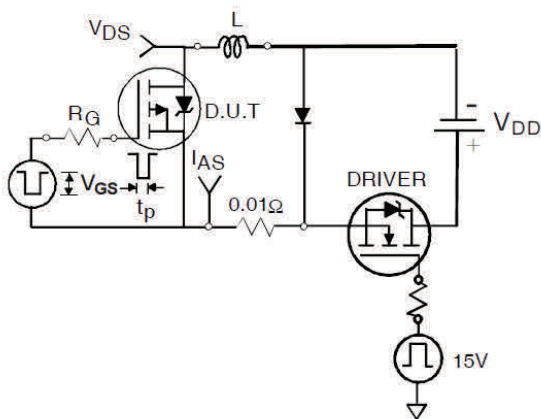


Fig 12a. Unclamped Inductive Test Circuit

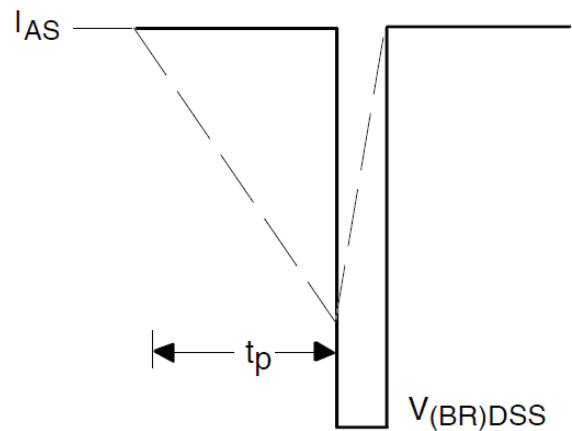


Fig 12b. Unclamped Inductive Waveforms

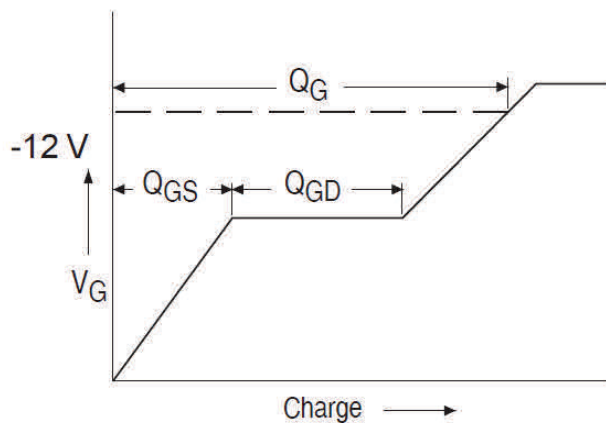


Fig 13a. Gate Charge Waveform

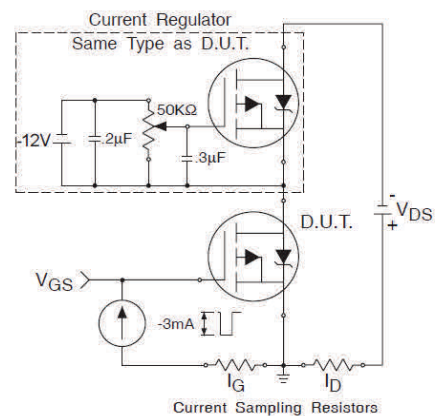


Fig 13b. Gate Charge Test Circuit

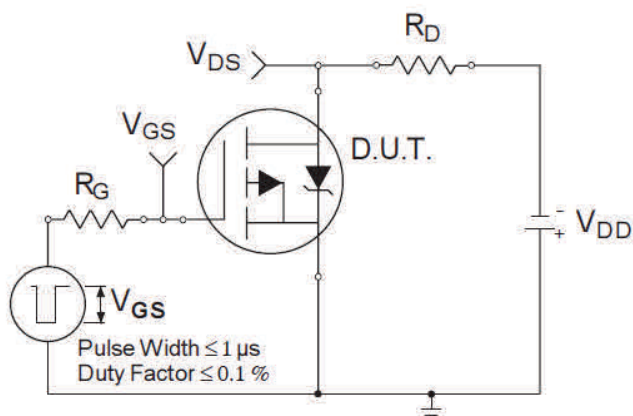


Fig 14a. Switching Time Test Circuit

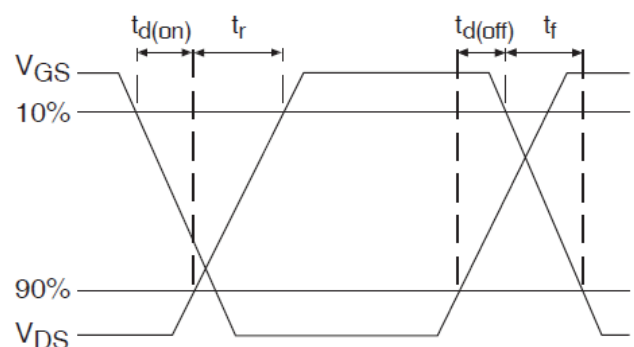
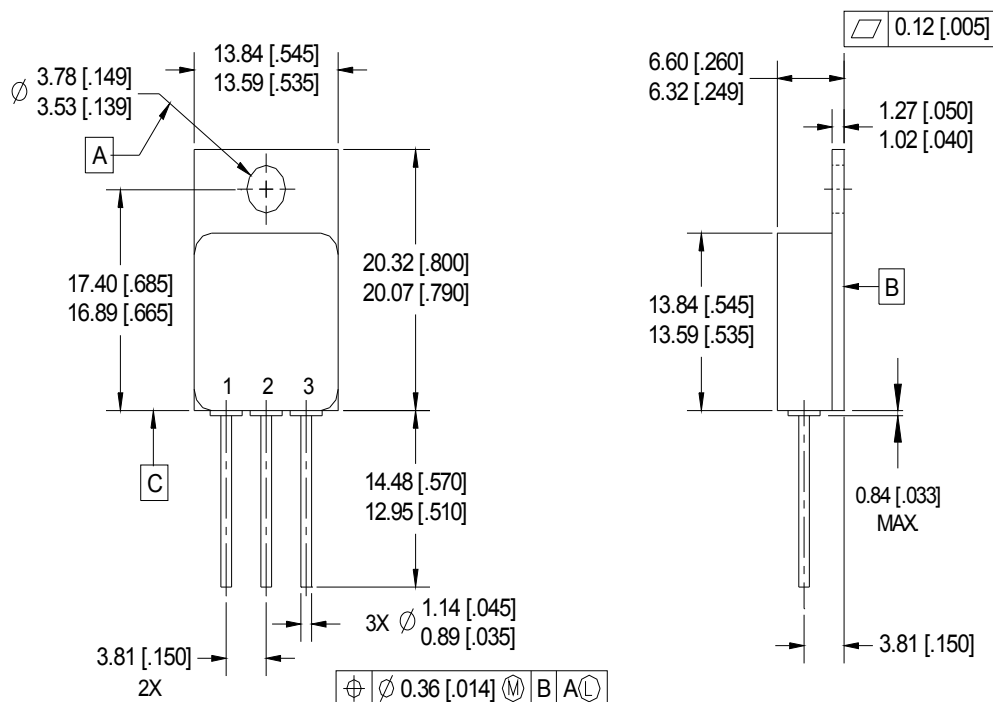


Fig 14b. Switching Time Waveforms

Case Outline and Dimensions - Low-Ohmic TO-254AA



NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. CONTROLLING DIMENSION: INCH.
4. CONFORMS TO JEDEC OUTLINE TO-254AA.

PIN ASSIGNMENTS

- 1 = DRAIN
2 = SOURCE
3 = GATE

BERYLLIA WARNING PER MIL-PRF-19500

Package containing beryllia shall not be ground, sandblasted, machined, or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxide packages shall not be placed in acids that will produce fumes containing beryllium.

IMPORTANT NOTICE

The information given in this document shall be in no event regarded as guarantee of conditions or characteristic. The data contained herein is a characterization of the component based on internal standards and is intended to demonstrate and provide guidance for typical part performance. It will require further evaluation, qualification and analysis to determine suitability in the application environment to confirm compliance to your system requirements.

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